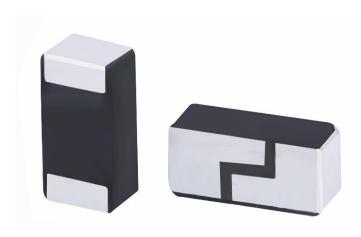


Series: Chip Antenna

TECHNICAL DATA SHEET

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C



Features:

2400-2483.5MHz

Size: 3.2 x 1.6 x 1.1mm

• Efficiency: 68 %

Gain: 1.3 dBi

Polarization: Linear

Power Handling: 5W

RoHS Compliant

Moisture Sensitivity Level MSL1

Applications:

Bluetooth, BLE, Zigbee, WiFi

· 2.4GHz ISM band radios

All dimensions are in mm / inches

Issue: 1946

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

ELECTRICAL SPECIFICATIONS

Frequency	2400-2483.5MHz
Nominal Impedance	50 Ω
Return Loss	-8dB
Radiation Pattern	Omni
Gain	1.3dBi
Efficiency	68%
Polarization	Linear
Power Withstanding	5W

MECHANICAL SPECIFICATIONS

Weight0.03 gOverall Length3.2 [0.126] MM [INCHES]Over all width1.6 [0.063] MM [INCHES]Over all thickness1.1 [0.043] MM [INCHES]MSL (Moisture Sensitivity Level)1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature -40~+85° C
Storage Temperature -40~+85° C
RoHS Compliant Yes

(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.



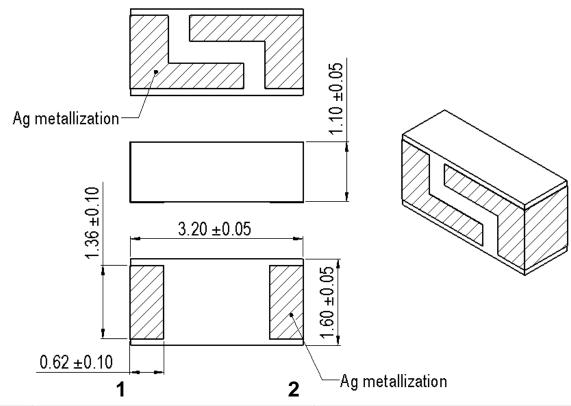


Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

MECHANICAL DRAWING



No.	Terminal Name	Terminal Dimensions
1	Feed /GND	0.62 x 1.36 mm
2	Feed /GND	0.62 x 1.36 mm
Antenna is symmetrical, either one of pads 1 or 2 can be used as feed terminal		

Note: This type of antenna is called loaded PIFA. One pad (on the bottom of the ceramic chip antenna) that feedline and GND are connected is a basic PIFA antenna structure. And, another pad on the other side that only GND is connected is for capacitive loading. Loaded capacitive value is optimized by the gap distance between two pads on the top surface. In PIFA, there is short mechanism usually in proximity to feed. This RF shorting affects impedance and current distribution mechanism of antenna. The actual antenna top face can seem to be mirrored, however it can be used same as the non-mirrored version. Please follow the design recommendation specified in this data sheet for either case.



Description: 2.4-2.4835GHz Ceramic SMT

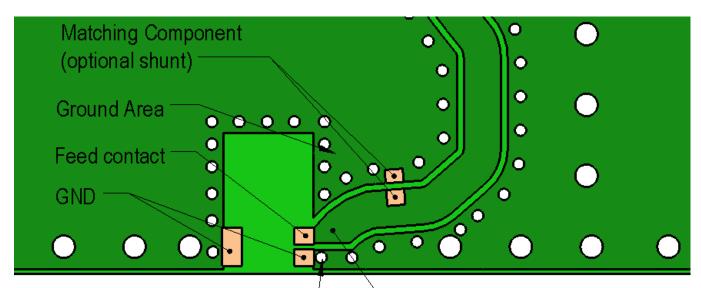
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

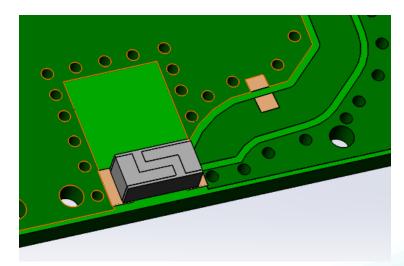
MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Ground cleared under antenna, clearance area 4 mm x 6.25mm



Ground Via Hole
Ground area should be
surround with ground via holes

Feed line 500hm
Any type of 50 0hm feed line can be used. inner layers on feed line area need to designed to give 50 0hm characteristics to feed line





Description: 2.4-2.4835GHz Ceramic SMT

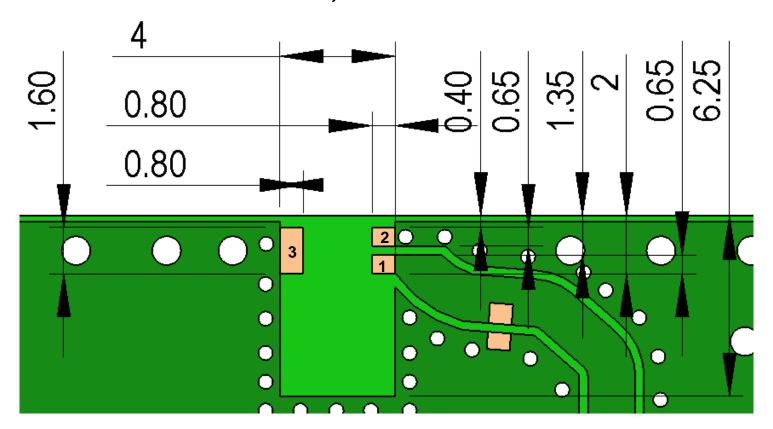
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended Antenna Pad Dimensions on PCB Layout (top surface) Ground cleared under antenna, clearance area 4 mm x 6.25 mm



PCB contact pads		
No.	Terminal Name	Terminal Dimensions
1	Feed	0,80 x 0,65 mm
2	GND	0,80 x 0,65 mm
3	GND	0,80 x 1,60 mm



Description: 2.4-2.4835GHz Ceramic SMT

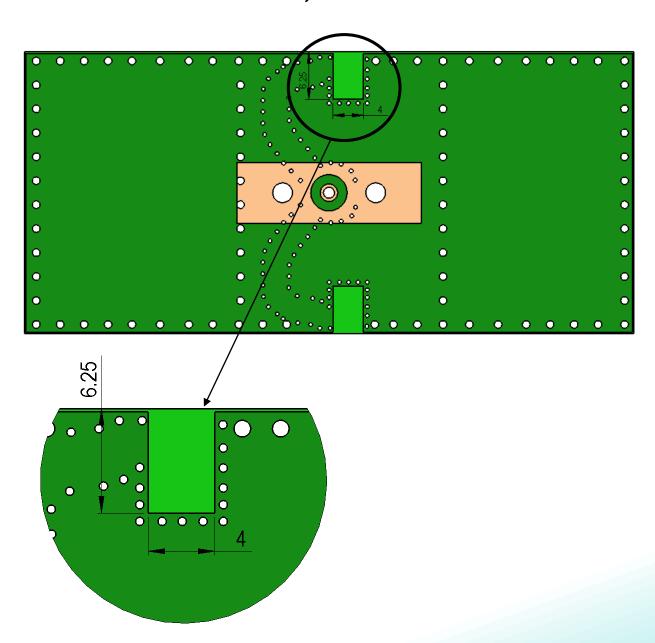
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended Antenna Pad Dimensions on PCB Layout (bottom surface) Ground cleared under antenna, clearance area 4 mm x 6.25 mm









Description: 2.4-2.4835GHz Ceramic SMT

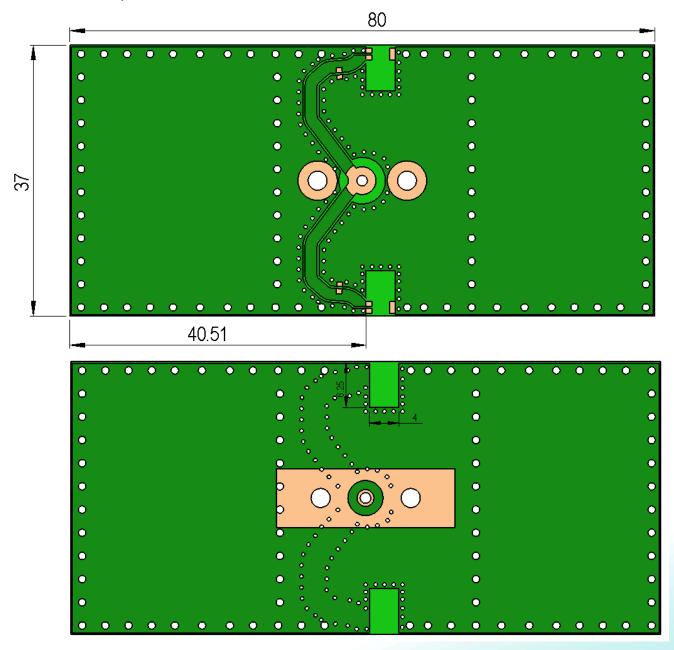
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37mm









Description: 2.4-2.4835GHz Ceramic SMT

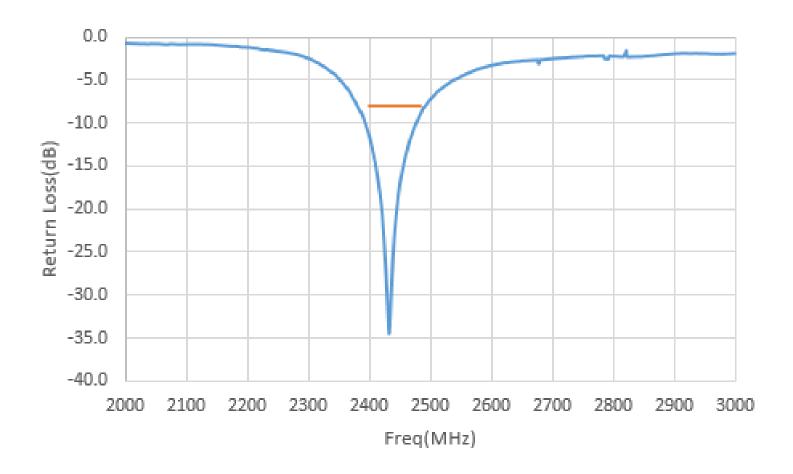
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

CHARTS

Return loss



(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.





Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

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CHARTS Efficiency(%) 80 70 60 50 Efficiency(%) 30 20 10

(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.

Issue: 1946



9



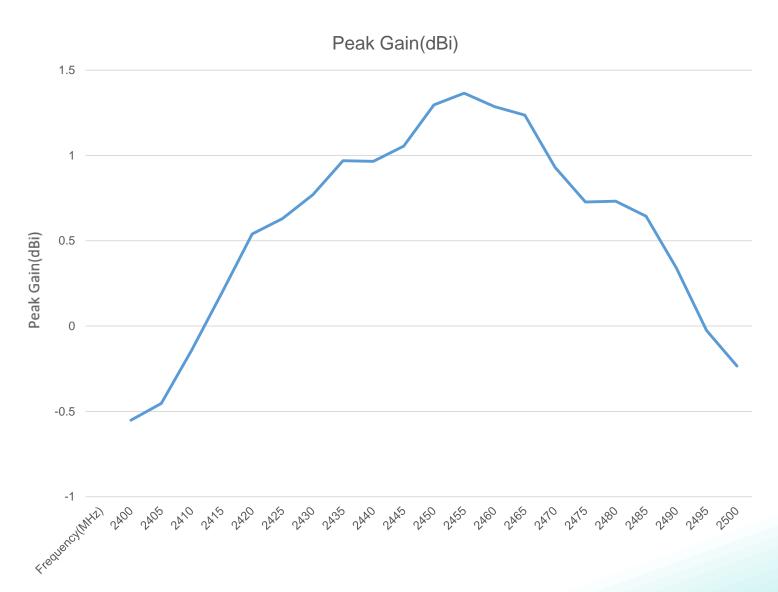
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

CHARTS

Peak Gain(dBi)



(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.





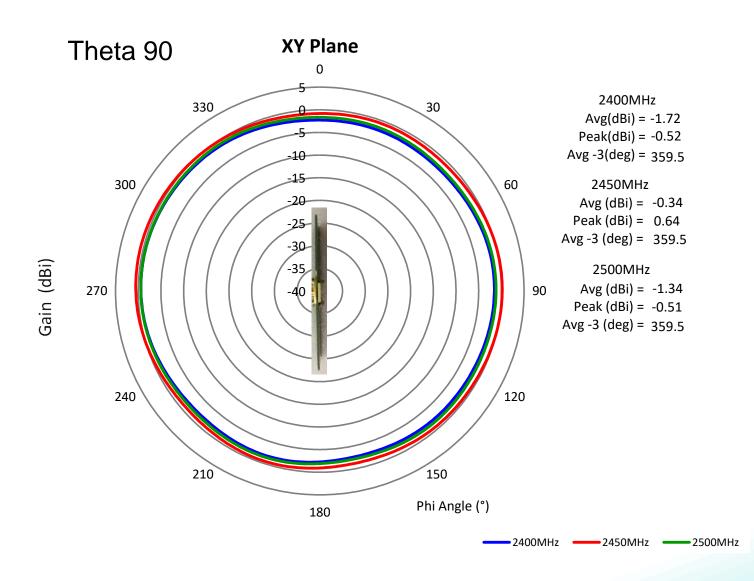
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.





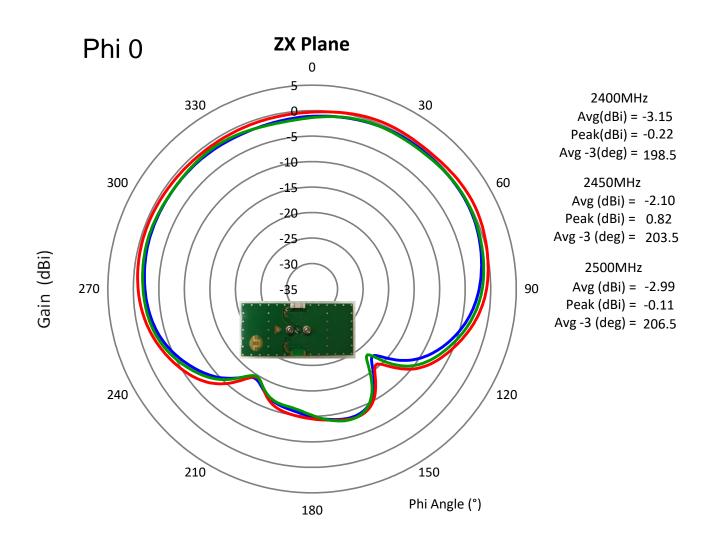
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.



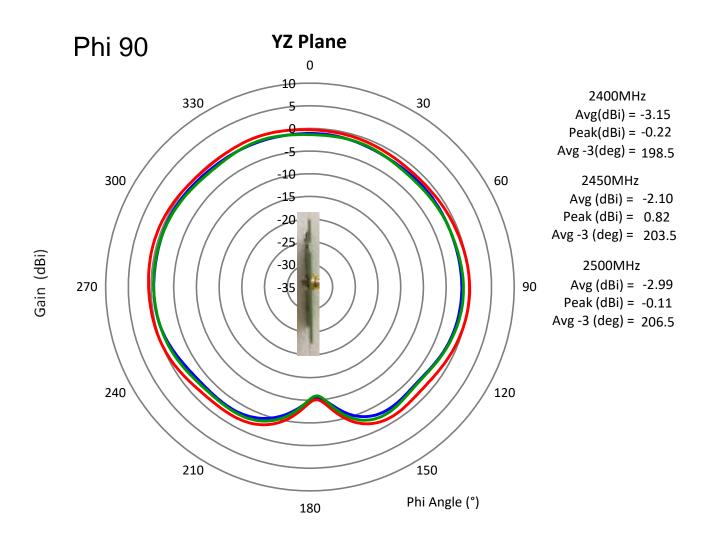
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*6.25mm clearance in free space. No matching component used.





Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

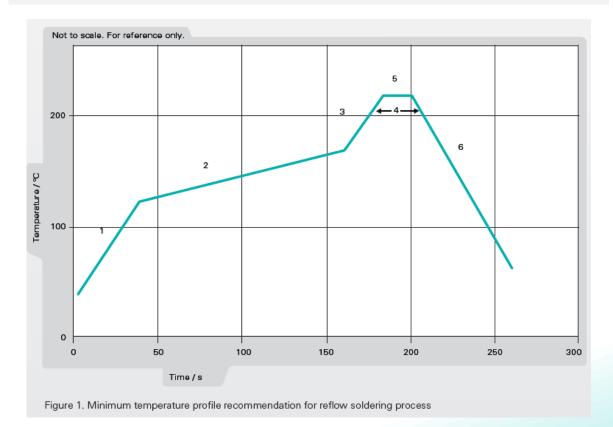
Series: Chip Antenna

Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile

presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



Issue: 1946



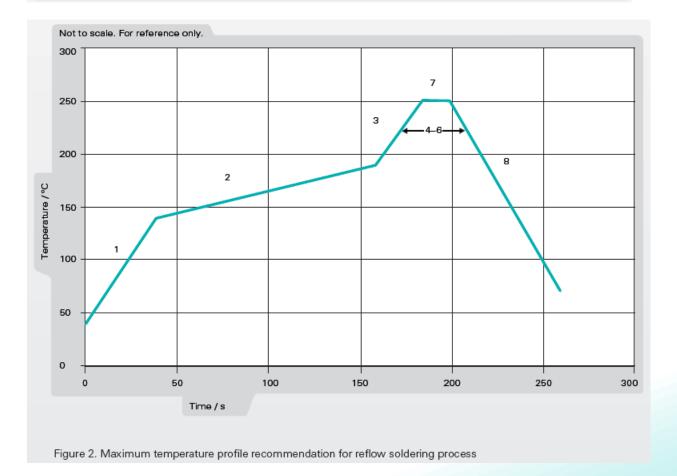
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s







Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

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PACKAGING-1

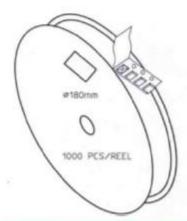
3000pcs antennas per 7" reel

5pcs 7" reel per inner package box

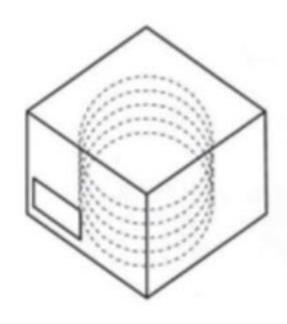
2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm







LEVEL

NOT MOISTURE SENSITIVE

1

These Devices do not require special storage conditions provided:

- They are maintained at conditions equal to or less than 30°C and 85% RH.
- They are solder reflowed at a peak body temperture which does not exceed 260°C.

Note: Level and body temperture defined by IPC/JEDEC J-STD-020